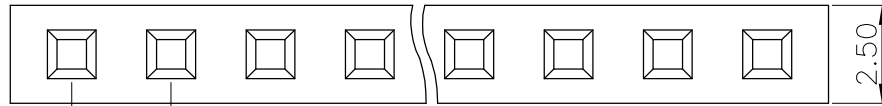


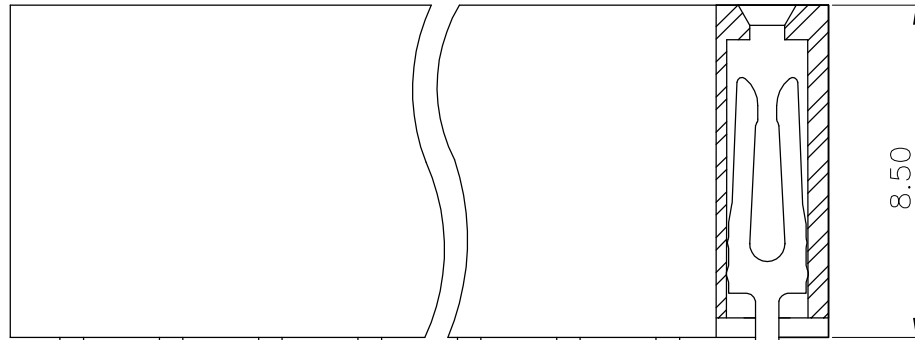
The product using material and processing must conform to the "WI-PZ-001" HSF technical standard control requirements

RoHS



2.54±0.15

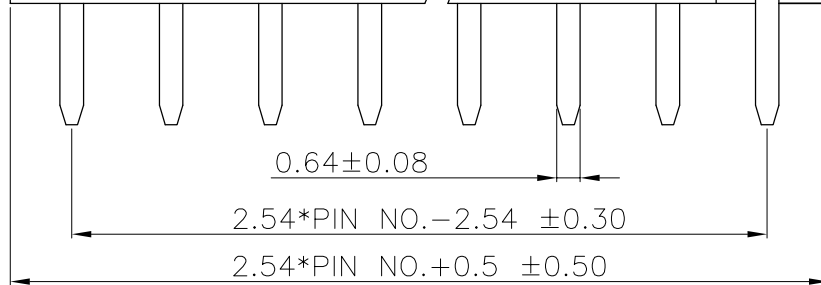
2.50



8.50

0.4±0.08

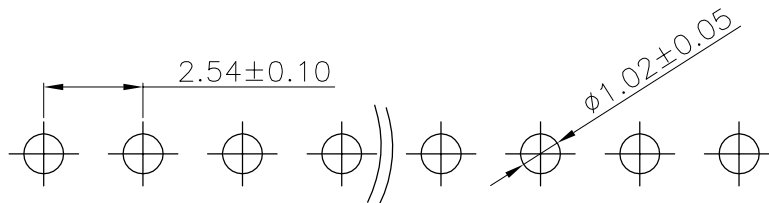
3.10



0.64±0.08

2.54*PIN NO.-2.54 ±0.30

2.54*PIN NO.+0.5 ±0.50



2.54±0.10

φ1.02±0.05

Recommended PCB layout

NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1-1.HOUSING: PA9T,UL94V-0
 - 1-2.CONTACTS: BRASS
- 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS: TIN/GOLD FLASH PLATED OVER ALL.
- 3.ELECTRICAL PERFORMANCE:
 - 3-1.CURRENT RATING: 3A AC/DC
 - 3-2.CONTACT RESISTANCE: 30 mΩ MAX
 - 3-3.INSULATION RESISTANCE: 1000MΩ Min
 - 3-4.DIELECTRIC WITHSTANDING : 500V AC
- 4.ENVIRONMENTAL PERFORMANCE:
 - 4-1.OPERATING TEMPERATURE: -40°C~+105°C.
- 5.PACKAGE SPEC: BOX/TRAY

6.P/N:

FH2541 85 F 0-1 XX 1 X X X 02

SERIES NO: _____ HOUSING: 1-PA9T

HEIGHT: _____
85: 8.5mm

MALE FEMALE: _____
F-FEMALE COLOR: A-BLACK

ANGLE: _____
0-180° PLATING: A-ALL AU G/F

ROW NO: _____
1-SINGLE ROW

PIN Q'PY: _____ TERMIPOINT: 1-DIP

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES		SCALE:	NAME	DATE	PART.NO:	DWG.NO:	
AO	NEW RELEASE	22.05.09	 LINEAR 0.0±0.35	 ANGLES X°REF±6°	1:1	Wang_jr	22.05.09	FH254185F0-1XX1XXX02	ENDE05	
					UNIT:mm	X°±3°	APPROVED	Han_Gao	22.05.09	TITLE:
			SIZE: A4	X°X' ±2°	DESIGNER	LanXuan_Hou	22.05.09	Pitch 2.54mm 180° 单排 DIP Y型排母	REV: A0	SHEET: 1/1
					DRAWN			H8.5W2.5 PC:3.1		

